

IMAPS Announces 2018 Society Awards

Thursday, November 8, 2018 – Research Triangle Park, NC- The International Microelectronics, Assembly and Packaging Society (IMAPS), has today released the names of the 2018 Society Award recipients. Each award has a specific criteria, the winner, being selected by an independent committee of judges, who has the highest score for the set criteria for each award.

The 2018 Awardees are as follows:

Lifetime Achievement – Greg Caswell, DfR Solutions, Inc. – This Award is given to the member who has made a lifetime of achievement and invaluable contributions to microelectronics technology; the microelectronics industrial development; and IMAPS. With the greatest of respect, we thank you for these contributions which are positively benefiting generations to come.

Daniel C. Hughes - E. Jan Vardaman – TechSearch International, Inc. – For her outstanding technical contributions supporting the microelectronics industry, her support and service to IMAPS.

Ashman/Wagman Technical Achievement Award – Scott Clary – Lockheed Martin Missiles and Fire Control - For his significant technical contributions to the electronics packaging industry and support of IMAPS.

Sidney J. Stein International – Hsiang-Chen Hsu – I-Shou University, St. John’s University - For significant international technical and leadership contributions to the microelectronics packaging industry, while participating and demonstrating support of IMAPS International activities to enhance the electronics packaging profession

Corporate Recognition –  **NAMICS**

For tremendous support of the Society at the local and national level.

Fellows of the Society – For their years of dedication and support of IMAPS in multiple leadership roles and for their numerous contributions to the Society worldwide and for their technical contribution to electronic packaging.

Mark Gerber – ASE US, Inc.

Osamu Suzuki – NAMICS Corp.

Lee J. Smith – UTAC

**Steve Adamson Memorial – Edmund Elburn - Center for Advanced Life Cycle Engineering,
University of Maryland**

In memory of our dearly departed IMAPS Past President Steve Adamson, the Microelectronics Foundation established an award recognizing a young leader in the Microelectronics field who exemplifies leadership and demonstrates outstanding contributions to IMAPS.

Outstanding Educator - Venky Sundaram – University of Georgia

President's Award – Susan Trulli - Raytheon Integrated Defense Systems

About IMAPS

The ***International Microelectronics Assembly and Packaging Society (IMAPS)*** is the largest society dedicated to the advancement and growth of microelectronics and electronics packaging technologies through professional education. The Society's **portfolio of technologies** is disseminated through symposia, conferences, workshops, professional development courses and other efforts. **IMAPS** currently has more than 3,000 members in the United States and more than 3,000 international members around the world.

Founded in 1967, **IMAPS** is the leading international microelectronics and electronic packaging society with professional members in 23 North American chapters and 21 international chapters. Members of the Society represent every discipline and specialty in the electronics industry and include both technical and marketing professionals. **IMAPS** hosts a variety of technical workshops and conferences and professional development courses that enable these professionals to enhance their careers. In addition, the ***Microelectronics Foundation*** provides annual grants to students involved in electronic packaging disciplines.

For more information, please visit www.imaps.org